# imall

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## ACPL-M60L

Small Outline, 5 Leads, High CMR, High-Speed, Logic Gate Optocouplers

## Data Sheet

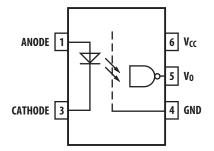
### Description

The ACPL-M60L is an optically coupled gate that combines a GaAsP light emitting diode and an integrated high gain photo detector. The output of the detector IC is an open collector Schottky-clamped transistor. The internal shield provides a guaranteed common mode transient immunity specification of 15 kV/µs at 3.3V operation.

This unique design provides maximum AC and DC circuit isolation while achieving LVTTL/LVCMOS compatibility. The optocoupler AC and DC operational parameters are guaranteed from -40°C to +100°C, allowing trouble-free system performance.

These optocouplers are suitable for high speed logic interfacing, input/output buffering, as line receivers in environments that conventional line receivers cannot tolerate and are recommended for use in extremely high ground or induced noise environments.

#### Figure 1 Functional Diagram



**CAUTION** It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation that may be induced by ESD. The components featured in this data sheet are not to be used in military or aerospace applications or environments.

#### Features

- Dual voltage operation (3.3V/5V)
- 15 kV/µs minimum Common Mode Rejection (CMR) at V<sub>CM</sub> = 1000V (3.3V operating voltage)
- High speed: 15 MBd typical
- LVTTL/LVCMOS compatible
- Low input current capability: 5 mA
- Guaranteed AC and DC performance over temperature: -40°C to +100°C
- Safety approvals; UL, CSA, IEC/EN/DIN EN 60747-5-5 (Pending)
- Surface mountable
- Very small, low profile JEDEC Registered package outline

#### Applications

- Isolated line receiver
- Computer-peripheral interfaces
- Microprocessor system interfaces
- Digital isolation for A/D, D/A conversion
- Switching power supply
- Instrument input/output isolation
- Ground loop elimination
- Pulse transformer replacement
- Field buses



## **Ordering Information**

ACPL-M60L is UL Recognized with 3750 Vrms for 1 minute per UL1577 and is approved under CSA Component Acceptance Notice #5, File CA 88324.

Part Number	Option	Package	Surface Mount	Tape and Reel	IEC/EN/DIN EN	Quantity
	<b>RoHS</b> Compliant		Surface mount	Tupe and Neer	60747-5-5	
ACPL-M60L	-000E	SO-5	Х			100 per tube
	-500E		Х	Х		1500 per reel
	-560E		Х	Х	Х	1500 per reel

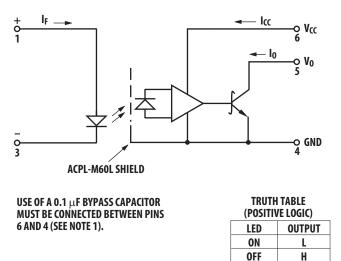
To order, choose a part number from the part number column and combine with the desired option from the option column to form an order entry.

Example 1:

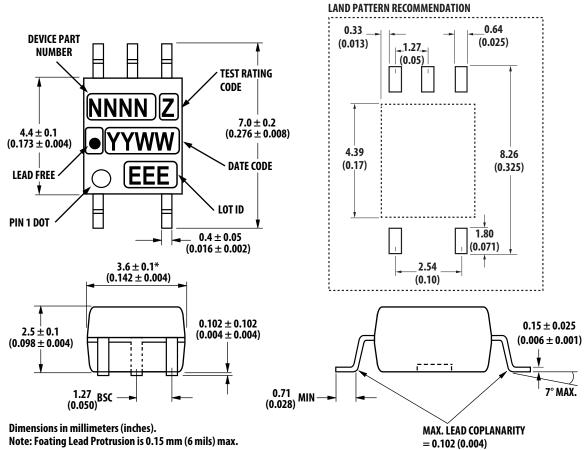
ACPL-M60L-500E to order product of Surface Mount SO-5 in Tape and Reel packaging with RoHS compliant.

Option data sheets are available. Contact your Broadcom sales representative or authorized distributor for information.

#### Figure 2 Schematic



#### Figure 3 Package Outline Drawing



\* Maximum Mold flash on each side is 0.15 mm (0.006).

#### **Solder Reflow Profile**

The recommended reflow soldering conditions are per JEDEC Standard J-STD-020 (latest revision). Non-halide flux should be used.

#### **Insulation and Safety-Related Specifications**

Parameter	Symbol	Value	Units	Conditions
Minimum External Air Gap (Clearance)	L (I01)	5	mm	Measured from input terminals to output terminals
Minimum External Tracking Path (Creepage)	L (I02)	5	mm	Measured from input terminals to output terminals
Minimum Internal Plastic Gap (Clearance)		0.08	mm	Through insulation distance, conductor to conductor
Tracking Resistance	СТІ	175	V	DIN IEC 112/VDE 0303 Part 1
Isolation Group (per DIN VDE 0109)		llla		Material Group DIN VDE 0109

#### IEC/EN/DIN EN 60747-5-5 Insulation Characteristics<sup>a</sup> (Option x60E)

Description	Symbol	Characteristic	Unit
Installation classification per DIN VDE 0110/39, Table 1			
for rated mains voltage $\leq$ 150 V <sub>rms</sub>		I - IV	
for rated mains voltage $\leq$ 300 V <sub>rms</sub>		I - IV	
for rated mains voltage $\leq$ 600 V <sub>rms</sub>		1 - 111	
Climatic Classification		55/100/21	
Pollution Degree (DIN VDE 0110/39)		2	
Maximum Working Insulation Voltage	V <sub>IORM</sub>	567	V <sub>peak</sub>
Input to Output Test Voltage, Method b <sup>a</sup>	V <sub>PR</sub>	1063	V <sub>peak</sub>
$V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Test with t <sub>m</sub> =1s, Partial discharge < 5 pC			
Input to Output Test Voltage, Method a <sup>a</sup>	V <sub>PR</sub>	907	V <sub>peak</sub>
$V_{IORM}  imes$ 1.6= $V_{PR'}$ Type and Sample Test, t <sub>m</sub> =10s, Partial discharge < 5 pC			
Highest Allowable Overvoltage (Transient Overvoltage t <sub>ini</sub> = 60s)	V <sub>IOTM</sub>	6000	V <sub>peak</sub>
Safety-limiting values – maximum values allowed in the event of a failure.			
Case Temperature	Τ <sub>S</sub>	175	°C
Input Current	I <sub>S, INPUT</sub>	150	ms
Output Power	P <sub>s</sub> , output	600	mW
Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V	R <sub>S</sub>	>10 <sup>9</sup>	Ω

a. Refer to the optocoupler section of the Isolation and Control Components Designer's Catalog, under Product Safety Regulations section, (IEC/EN/DIN EN 60747-5-5) for a detailed description of Method a and Method b partial discharge test profiles.

**NOTE** These optocouplers are suitable for *safe electrical isolation* only within the safety limit data. Maintenance of the safety limit data shall be ensured by means of protective circuits.

### Absolute Maximum Ratings (No Derating Required up to 85°C)

Parameter	Symbol	Min.	Max.	Units	Note
Storage Temperature	Τ <sub>S</sub>	-55	125	°C	
Operating Temperature†	T <sub>A</sub>	-40	100	°C	
Average Forward Input Current	١ <sub>F</sub>	—	20	mA	а
Reverse Input Voltage	V <sub>R</sub>	—	5	V	
Input Power Dissipation	PI	—	40	mW	
Supply Voltage (1 minute maximum)	V <sub>CC</sub>	—	7	V	
Output Collector Current	۱ <sub>0</sub>	—	50	mA	
Output Collector Voltage	V <sub>O</sub>	—	7	V	
Output Collector Power Dissipation	P <sub>O</sub>	—	85	mW	
Solder Reflow Temperature Profile		See the Pac	kage Outline D	rawing.	

a. Peaking circuits may produce transient input currents up to 50 mA, 50 ns maximum pulse width, provided average current does not exceed 20 mA.

### **Recommended Operating Conditions**

Parameter	Symbol	Min.	Max.	Units	Conditions
Input Current, Low Level	$I_{FL}^{a}$	0	250	μΑ	
Input Current, High Level <sup>b</sup>	I <sub>FH</sub> c	5	15	mA	
		6		mA	$2.7V \le V_{CC} \le 3.6V$ , $T_A = 85^{\circ}C$ to $100^{\circ}C$
Power Supply Voltage	V <sub>CC</sub>	2.7	3.6	V	
		4.5	5.5	V	
Operating Temperature	T <sub>A</sub>	-40	85	°C	
Fan Out (at $R_L = 1 \ k\Omega$ ) <sup>b</sup>	N	—	5	TTL Loads	
Output Pull-up Resistor	RL	330	4 k	Ω	

a. The off condition can also be guaranteed by ensuring that  $V_{FL} \leq 0.8V.$ 

b. Peaking circuits may produce transient input currents up to 50 mA, 50 ns maximum pulse width, provided average current does not exceed 20 mA.

c. At T<sub>A</sub> = -40°C to 85°C, the initial switching threshold is 5 mA or less. It is recommended that 6.3 mA to 10 mA be used for best performance and to permit at least a 20% LED degradation guardband.

Over recommended operating condition ( $T_A = -40^{\circ}C$  to  $+100^{\circ}C$ ,  $2.7V \le V_{DD} \le 3.6V$ ) unless otherwise specified. All Typical specifications at  $V_{CC} = 3.3V$ ,  $T_A = 25^{\circ}C$ .

Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions	Fig.	Note
High Level Output Current	I <sub>OH</sub> a	—	4.5	50	μΑ	$V_{CC} = 3.3V, V_{O} = 3.3V,$ $I_{F} = 250 \ \mu A$	4	
Input Threshold Current	I <sub>TH</sub>	—	3.0	5.0	mA	$T_A = -40^{\circ}$ C to 85°C V <sub>CC</sub> = 3.3V, V <sub>O</sub> = 0.6V, I <sub>OL</sub> (Sinking) = 13 mA	6	
				6.0	mA	$V_{CC} = 3.3V, V_O = 0.6V,$ $I_{OL}$ (Sinking) = 13 mA	6	
Low Level Output Voltage	V <sub>OL</sub> <sup>a</sup>	—	0.35	0.6	V	V <sub>CC</sub> = 3.3 V, I <sub>F</sub> = 5 mA, I <sub>OL</sub> (Sinking) = 13 mA	8, 10	
High Level Supply Current	I <sub>CCH</sub>	—	4.7	7.0	mA	$I_{\rm F} = 0  {\rm mA}, V_{\rm CC} = 3.3 {\rm V}$		
Low Level Supply Current	I <sub>CCL</sub>	—	7.0	10.0	mA	I <sub>F</sub> = 10 mA, V <sub>CC</sub> = 3.3V		
Input Forward Voltage	V <sub>F</sub>	1.4	1.5	1.75 <sup>a</sup>	V	T <sub>A</sub> = 25°C, I <sub>F</sub> = 10 mA	12	
Input Reverse Breakdown Voltage	BV <sub>R</sub> <sup>a</sup>	5	—	—	V	I <sub>R</sub> = 10 μA		
Input Diode Temperature Coefficient	$\Delta V_F / \Delta T_A$	—	-1.6	—	mV/°C	I <sub>F</sub> = 10 mA		
Input-Output Insulation	V <sub>ISO</sub>	3750	—	—	V <sub>RMS</sub>	$R_{H} \le 50\%$ , t = 1 min.		b,c
Input Capacitance	C <sub>IN</sub>	—	60	—	pF	$f = 1 MHz, V_F = 0V$		

a. The JEDEC Registration specifies 0°C to +70°C. Broadcom specifies -40°C to + 100°C.

b. Device considered a two terminal device: pins 1 and 3 shorted together, and pins 4, 5, and 6 shorted together.

c. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage  $\geq$  4500 V<sub>RMS</sub> for 1 second (Leakage detection current limit, I<sub>LO</sub>  $\leq$  5 µA).

### **Electrical Specifications**

Over recommended temperature ( $T_A = -40^{\circ}$ C to  $+100^{\circ}$ ,  $4.5V \le V_{DD} \le 5.5V$ ) unless otherwise specified. All Typical specifications at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}$ C.

Parameter	Symbol	Min.	Typ. <sup>a</sup>	Max.	Units	Test Conditions	Fig.	Note
High Level Output Current	I <sub>OH</sub>	_	5.5	100	μA	V <sub>CC</sub> = 5.5V, V <sub>O</sub> = 5.5V, I <sub>F</sub> = 250 μA	5	
Input Threshold Current	I <sub>TH</sub>	_	2	5	mA	$V_{CC} = 5.5V, I_O \ge 13 \text{ mA},$ $V_O = 0.6V$	7	
Low Level Output Voltage	V <sub>OL</sub>	_	0.4	0.6	V	V <sub>CC</sub> = 5.5V, I <sub>F</sub> = 5 mA, I <sub>OL</sub> (Sinking) = 13 mA	9, 11	
High Level Supply Current	I <sub>CCH</sub>		4	7.5	mA	$V_{CC} = 5.5V, I_F = 0 \text{ mA}$		
Low Level Supply Current	I <sub>CCL</sub>	_	6	10.5	mA	V <sub>CC</sub> = 5.5V, I <sub>F</sub> = 10 mA		
Input Forward Voltage	V <sub>F</sub>	1.4	1.5	1.75	V	T <sub>A</sub> = 25°C, I <sub>F</sub> = 10 mA	12	
		1.3		1.85		I <sub>F</sub> = 10 mA	_	
Input Reverse Breakdown Voltage	BV <sub>R</sub>	5	—	—	V	I <sub>R</sub> = 10 μA		
Input Diode Temperature Coefficient	$\Delta V_{\rm F} / \Delta T_{\rm A}$	_	-1.6	—	mV/°C	I <sub>F</sub> = 10 mA		
Input-Output Insulation	V <sub>ISO</sub>	3750			V <sub>RMS</sub>	$RH \le 50\%$ , t = 1 min.		b,c
Input Capacitance	C <sub>IN</sub>	_	60	—	pF	$V_F = 0V, f = 1 MHz$		

a. All typicals at  $T_A = 25^{\circ}C$ ,  $V_{CC} = 5V$ .

b. Device considered a two terminal device: pins 1 and 3 shorted together, and pins 4, 5, and 6 shorted together.

c. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage  $\ge$  4500 V<sub>RMS</sub> for 1 second (Leakage detection current limit, I<sub>LO</sub>  $\le$  5 µA).

#### **Switching Specifications**

Over recommended temperature ( $T_A = -40^{\circ}$ C to  $+100^{\circ}$ C),  $V_{CC} = 3.3$ V,  $I_F = 7.5$  mA unless otherwise specified. All Typical specifications at  $T_A = 25^{\circ}$ C,  $V_{CC} = 3.3$ V.

#### **Table 1 Switching Specifications**

Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions	Fig.	Note
Propagation Delay Time to High Output Level	t <sub>PLH</sub>	—	—	90	ns	$T_A = -40^{\circ}$ C to 85°C, $R_L = 350\Omega$ , $C_L = 15 \text{ pF}$	13, 14	a b
			—	95	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Propagation Delay Time to Low Output Level	t <sub>PHL</sub>	_	—	75	ns	$T_A = -40^{\circ}$ C to 85°C, $R_L = 350\Omega$ , $C_L = 15 \text{ pF}$	13, 14	b,c
			—	90	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Pulse Width Distortion	t <sub>PHL</sub> – t <sub>PLH</sub>	_	—	25	ns	$T_A = -40^{\circ}$ C to 85°C, $R_L = 350\Omega$ , $C_L = 15 \text{ pF}$	16	b
		_	—	30	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Propagation Delay Skew	t <sub>PSK</sub>		_	40	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Output Rise Time (10-90%)	t <sub>r</sub>		45	—	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Output Fall Time (90-10%)	t <sub>f</sub>		20	—	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		

a. The t<sub>PLH</sub> propagation delay is measured from the 3.75 mA point on the falling edge of the input pulse to the 1.5 V point on the rising edge of the output pulse.

b. See test circuit for measurement details.

c. The t<sub>PHL</sub> propagation delay is measured from the 3.75 mA point on the rising edge of the input pulse to the 1.5 V point on the falling edge of the output pulse.

**NOTE** JEDEC registered data for the 6N137.

#### **Switching Specifications**

Over recommended temperature ( $T_A = -40^{\circ}$ C to  $100^{\circ}$ C),  $V_{CC} = 5$ V,  $I_F = 7.5$  mA unless otherwise specified. All Typical specifications at  $T_A = 25^{\circ}$ C,  $V_{CC} = 5$ V.

#### Table 2 Switching Specifications

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	Figure	Note
Propagation Delay Time to High Output Level	t <sub>PLH</sub>	20	48	75	ns	T <sub>A</sub> = 25°C, R <sub>L</sub> =350Ω, CL=15 pF	13, 15	a b
				100		$R_L$ =350 $\Omega$ , $C_L$ =15 pF		
Propagation Delay Time to Low Output Level	tPHL	25	50	75	ns	$T_A = 25$ °C, $R_L = 350$ Ω, $C_L = 15 \text{ pF}$	13, 15	b c
				100		$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Pulse Width Distortion	t <sub>PHL</sub> – t <sub>PLH</sub>	_	3.5	35	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$	17	b
Propagation Delay Skew	t <sub>PSK</sub>		—	40	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Output Rise Time (10%–90%)	t <sub>rise</sub>	_	24	—	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		
Output Fall Time (10%–90%)	t <sub>fall</sub>	_	10	-	ns	$R_L = 350\Omega, C_L = 15 \text{ pF}$		

a. The t<sub>PLH</sub> propagation delay is measured from the 3.75 mA point on the falling edge of the input pulse to the 1.5 V point on the rising edge of the output pulse.

b. See test circuit for measurement details.

c. The t<sub>PHL</sub> propagation delay is measured from the 3.75 mA point on the rising edge of the input pulse to the 1.5 V point on the falling edge of the output pulse.

## **Transient Immunity**

Parameter	Sym.	Min.	Тур.	Units	T	Figure	Note	
Logic High Common Mode Transient Immunity	CM <sub>H</sub>	15,000	25,000	V/µs	V <sub>CM</sub>   = 1000V	$V_{CC} = 3.3V, I_F = 0 \text{ mA},$ $V_{O(MIN)} = 2V, R_L = 350\Omega,$ $T_A = 25^{\circ}C$	18	a b
		10,000	15,000			$V_{CC} = 5V, I_F = 0 \text{ mA},$ $V_{O(MIN)} = 2V, R_L = 350\Omega,$ $T_A = 25^{\circ}C$	18	a b ,
Logic Low Common Mode Transient Immunity	CM <sub>L</sub>	15,000	25,000	V/µs	V <sub>CM</sub>   = 1000V	$V_{CC} = 3.3V$ , $I_F = 7.5$ mA, $V_{O(MAX)} = 0.8V$ , $R_L = 350\Omega$ , TA = 25°C	18	b,c
		10,000	15,000			$V_{CC} = 5V$ , $I_F = 7.5 \text{ mA}$ , $V_{O(MIN)} = 0.8V$ , $R_L = 350\Omega$ , $T_A = 25^{\circ}C$	18	b c

a. CM<sub>H</sub> is the maximum tolerable rate of rise on the common mode voltage to assure that the output will remain in a high logic state (that is, V<sub>o</sub> > 2.0V).

b. For sinusoidal voltages,  $(|dV_{CM}| / dt)_{max} = \pi f_{CM}V_{CM}$  (p-p).

c. CM<sub>L</sub> is the maximum tolerable rate of fall of the common mode voltage to assure that the output will remain in a low logic state (that is, V<sub>o</sub> < 0.8V).

Figure 4 Typical High Level Output Current vs. Temperature

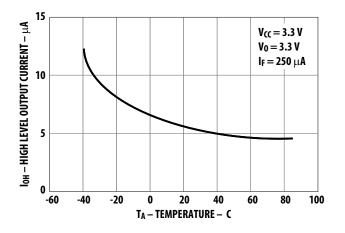


Figure 6 Typical Input Threshold Current vs. Temperature

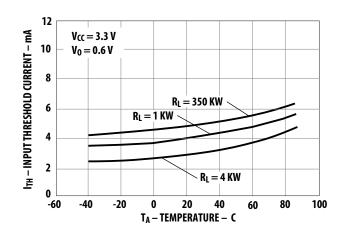


Figure 8 Typical Low Level Output Voltage vs. Temperature

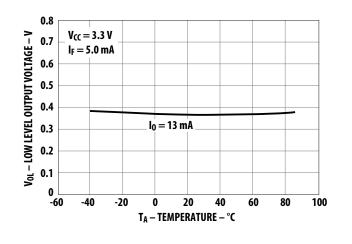


Figure 5 Typical High Level Output Current vs. Temperature

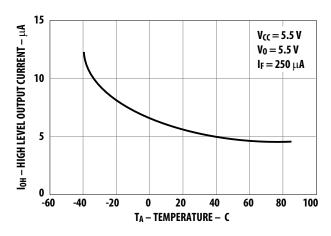


Figure 7 Typical Input Threshold Current vs. Temperature

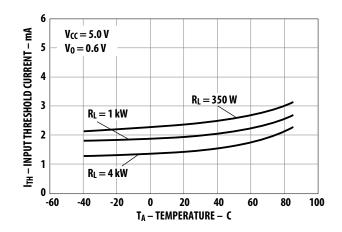


Figure 9 Typical Low Level Output Voltage vs. Temperature

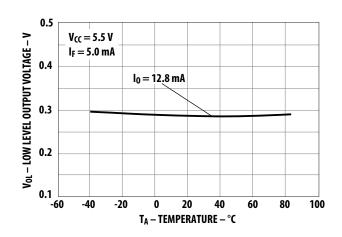


Figure 10 Typical Low Level Output Current vs. Temperature

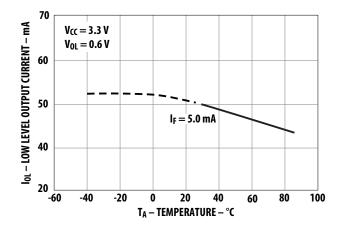


Figure 11 Typical Low Level Output Current vs. Temperature

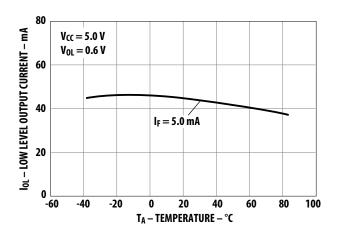
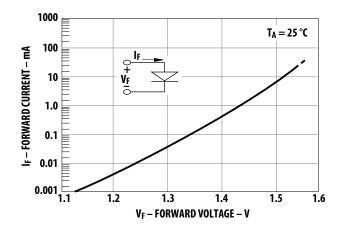
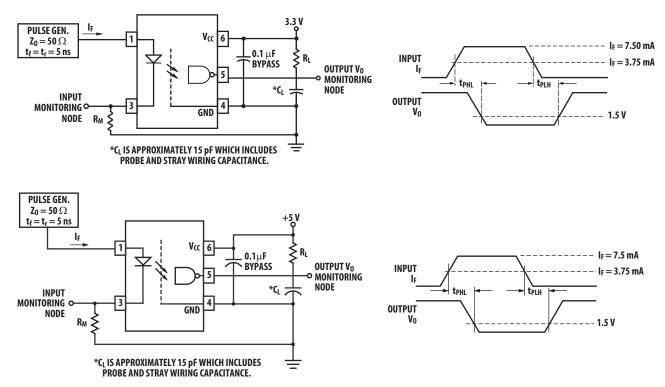


Figure 12 Typical Input Diode Forward Characteristic







#### Figure 14 Typical Propagation Delay vs. Temperature

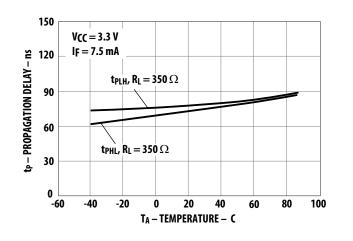
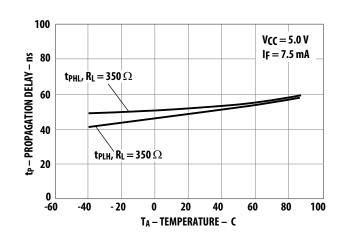


Figure 15 Typical Propagation Delay vs. Temperature



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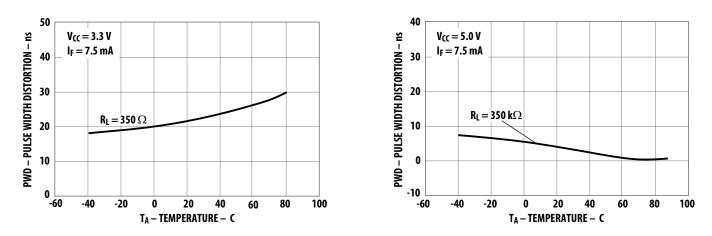
 $\mathsf{CM}_\mathsf{L}$ 

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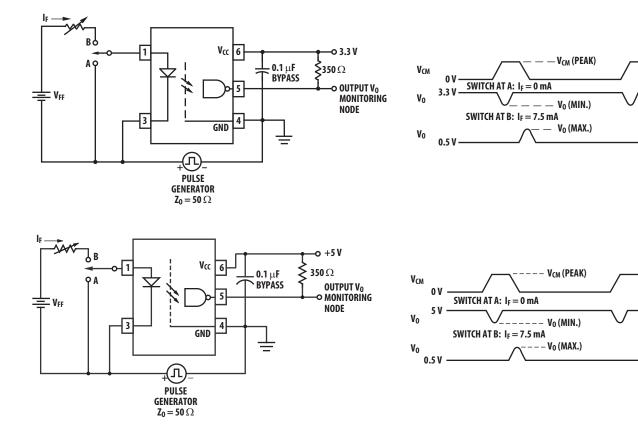
 $\mathsf{CM}_\mathsf{L}$ 

Figure 16 Typical Pulse Width Distortion vs. Temperature

Figure 17 Typical Pulse Width Distortion vs. Temperature







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